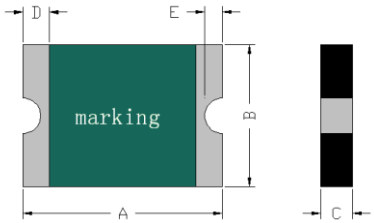
# TSML100

## Features

- ☐ Small size of 0603
- ☐ Low resistance
- ☐ Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- ☐ Fast time-to-trip
- ☐ Agency Recognition: UL、CSA、TUV




## Product Dimensions (mm)

| Part number | A | B | C | D | E | Part marking |
|---|---|---|---|---|---|---|
| | Typ. | Typ. | Typ. | Typ. | Typ. | |
| TSML100 | 1.60±0.20 | 0.80±0.20 | 0.50±0.20 | 0.35±0.15 | 0.20±0.15 | — |



## Electrical Characteristics

| Part number | $I_H$ | $I_T$ | $V_{max}$ | $I_{max}$ | $T_{trip}$ | | $Pd_{typ}$ | $R_{min}$ | $R_{1max}$ |
|---|---|---|---|---|---|---|---|---|---|
| | (A) | (A) | (V) | (A) | Current(A) | Time(S) | (W) | (Ω) | (Ω) |
| TSML100 | 1.00 | 1.80 | 6 | 50 | 8.0 | 2 | 0.5 | 0.030 | 0.150 |

$I_H$=Hold current: maximum current at which the device will not trip at 25℃ still air.

$I_T$=Trip current: minimum current at which the device will always trip at 25℃ still air.

$V_{max}$=Maximum voltage device can withstand without damage at rated current.

$I_{max}$=Maximum fault current device can withstand without damage at rated voltage.

$T_{trip}$=Maximum time to trip(s) at assigned current.

$Pd_{typ}$=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

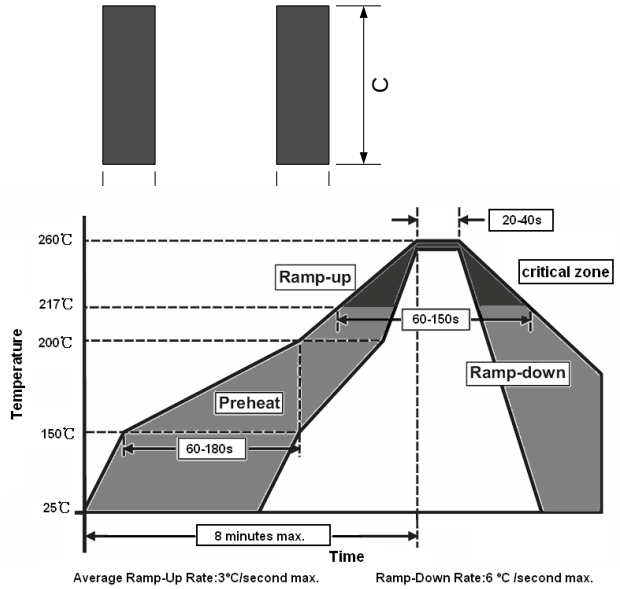
$R_{min}$=Minimum device resistance at 25℃ prior to tripping.

$R_{1max}$=Maximum device resistance measured in the nontripped state 1 hour post reflow.

## Thermal Derating

| LP-TSML100 | Maximum ambient operating temperature(℃) | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| | -40 | -20 | 0 | 20 | 25 | 40 | 50 | 60 | 70 | 85 |
| Hold Current (A) | 1.34 | 1.17 | 1.08 | 1.02 | 1.00 | 0.82 | 0.74 | 0.68 | 0.57 | 0.40 |
| Trip Current (A) | 2.68 | 2.34 | 2.16 | 2.04 | 2.00 | 1.64 | 1.48 | 1.36 | 1.14 | 0.80 |

## Solder Reflow Recommendations




**Solder Pad Layouts**

| Part number | A (mm) | B (mm) | C (mm) |
|---|---|---|---|
| TSML100 | 0.60 | 1.10 | 1.00 |

* Recommended reflow methods: IR, Vapor phase, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

**Notes:**

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

### Package Information

Tape & Reel: 5000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

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